

Title (en)

DEVICE AND METHOD FOR THE ETCHING OF SUBSTRATES

Title (de)

VORRICHTUNG UND VERFAHREN ZUM ÄTZEN VON SUBSTRATEN

Title (fr)

PROCEDE ET DISPOSITIF DE GRAVURE DE SUBSTRATS

Publication

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Application

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Abstract (en)

[origin: WO2006094657A1] According to the invention, the etching of, for example, conductor structures on circuit boards (21) with etching fluid may be improved, whereby the etching fluid is sprayed onto the circuit board (21) as an aerosol spray (17), or similar. By means of contacting a corresponding spraying device (13, 14) to one pole and the circuit board (21) to the other pole of a DC supply (23), the etching process can be assisted and in particular, accelerated.

IPC 8 full level

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